

Final Product/Process Change Notification Document #: FPCN21386XA

Issue Date: 20 July 2016

Title of Change:	Change of Mold compound and Lead frame design in ATPAK.						
Proposed first ship date:	27 October 2016						
Contact information:	Contact your local ON Semiconductor Sales Office or < Yasunari.Noguchi @onsemi.com>						
Samples:	Contact your local ON Semiconductor Sales Office						
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume @onsemi.com >						
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.						
Type of notification.	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>						
Change Part Identification:	Affected products will be identified with date code.						
Change category:	ange category: Wafer Fab Change Assembly Change Test Change Other						
Change Sub-Category(s): ☐ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Product specific change ☐ Other:							
Sites Affected: All site(s) not applicable ON Semiconductor site(s): ON Shenzhen, China External Foundry/Subcon site(s)							
Description and Purpose:							
This is a Final Process Change Notification to announce the change of mold compound and lead frame design.							
1) The change of mold compound from GE-1030 to EME-G700.							
2) The change of lead frame design to add V-notch on a flag.							
	Before change After change						
Mold compound		GE-1030	EME-G700				
Lead frame		Lead frame without V-notch for prevent solder flow on flag.	ng Lead frame with V-notch for preventing solder flow on flag.				

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Reliability Data Summary:

QV DEVICE NAME ATP304-TL-H

PACKAGE: ATPAK / DPAK (Single Gauge)

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/231
HTGB	JESD22-A108 Ta=150°C, 100% max rated Vgss		1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 сус	0/231
HAST	JESD22-A110	-A110 130°C, 85% RH, 18.8psig, bias		0/231
AC	JSTD020 JESD-A102	Tj=121°C, RH=100%, Pressure=15psig	96 hrs	0/231

PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta = 265C, 10 sec	0/90

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
ATP101-TL-H	ATP304-TL-H
ATP101-V-TL-H	
ATP106-TL-H	
ATP108-TL-H	
ATP112-TL-H	
ATP114-TL-H	
ATP302-TL-H	

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